

Amendments to the Specification:

Please amend the specification as follows.

Page 13, please replace the second paragraph and replace it with the following amended paragraph:

A semiconductor light emitting device shown in Figure 1 comprises a metallic support plate 1 formed with a recess 1a; a light-reflective reflector 3 mounted in recess 1a of support plate 1 in electrically insulating relation to support plate 1, and formed with a hole 3a upwardly expanding; a light emitting diode 2 mounted on recess 1a of support plate 1 within hole 3a of reflector 3, one electrode (a bottom electrode) of the light emitting diode 2 being electrically connected to support plate 1; a first wiring conductor 4 electrically connected to support plate 1; a second wiring conductor 5 electrically connected to the other electrode (a top electrode) of light emitting diode 2; a lead wire 8 for electrically connecting light emitting diode 2 and reflector 3; a heat-resistible plastic encapsulant 6 for encapsulating outer periphery of reflector 3, upper and side surfaces 1c, 1d of support plate 1, each inner end of first and second wiring conductors 4, 5; and a lens 7 for covering hole 3a of reflector 3 and upper surface 6a of encapsulant 6. The encapsulant has an opening 6b.